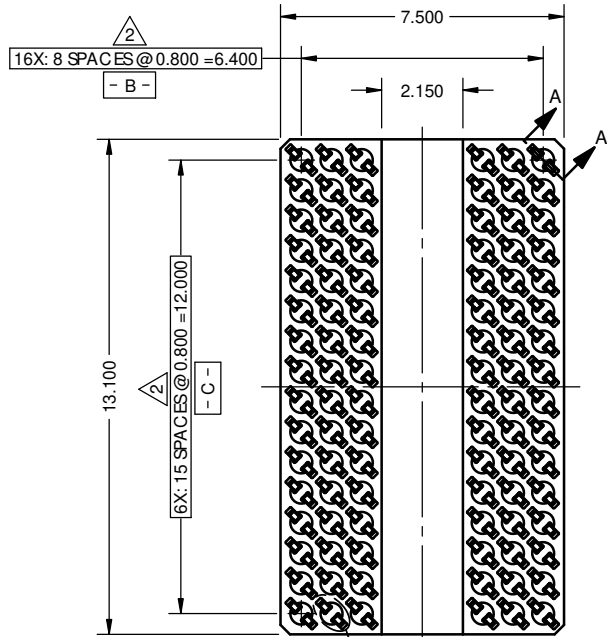


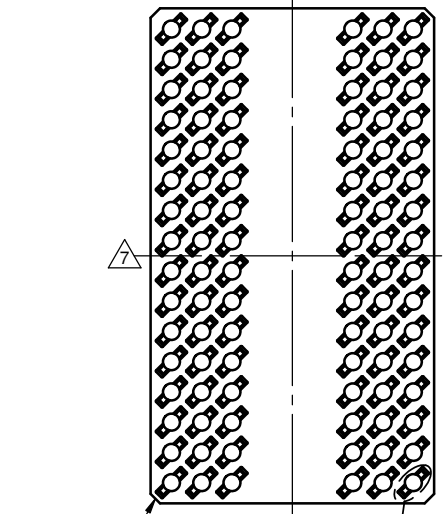
REV	ECO	BY	DESCRIPTION	APV	DATE
A	31470	AS	Initial Design	NSJ	01/30/14



0.03 / □ 10
- A -

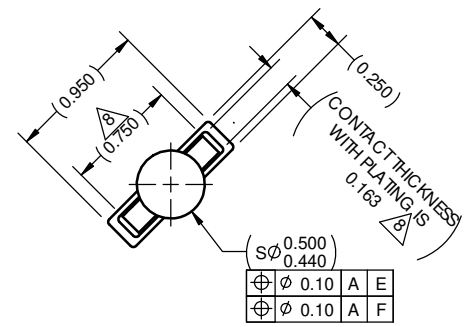
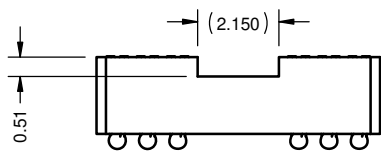
2.030±0.030

0.13
BOTTOM OF SOLDER BALLS



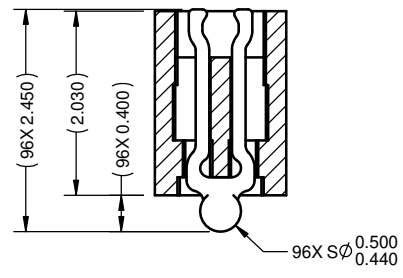
Notes:

- Reference HSI0 Technologies specification 103862-0004 for solder attachment.
- Locates center of contact/slot.
- Reference HSI0 Technologies specification 103863-0001 for application notes.
- Footprint part number is 104311-0058.
- Datum -B- and -C- are determined by $\phi 0.580$ opening in corner slots.
- Unless otherwise noted, all features are located $\oplus 0.10$ A B C
- E - Center of ball pattern.
- F - Center of contact.

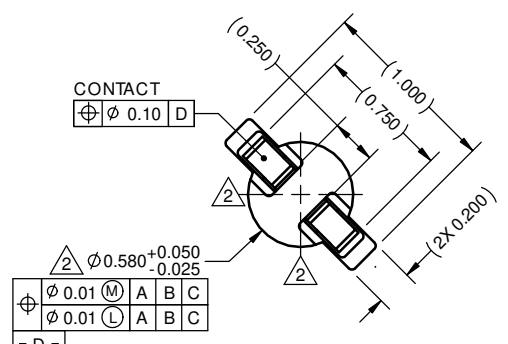


DETAIL C (96X)
SCALE 4:1

Parts List	
Part Number	Description
103864-0060	PRESS, DEVICE INSERT, GRYP 7.5X13.1 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4X53 (SOLD SEPARATELY)



SECTION A-A
SCALE 2:1



$\phi 0.580^{+0.050}_{-0.025}$
 $\phi 0.01$ (M) A B C
 $\phi 0.01$ (L) A B C
- D -

DETAIL B (96X)
SCALE 4:1

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN MILLIMETERS
TOLERANCES
ANGULAR ± 1°
XX ± 0.25
XXX ± 0.10
XXXX ± 0.050

INTERPRET GEOMETRIC TOLERANCING PER:
MATERIAL
SEE BOM
FINISH
DO NOT SCALE DRAWING

NAME	DATE
AS	01/30/14
MP	01/30/14

LEGEND:

- △ NOTE CALLOUT
- REVISION CHANGE
- ITEM NUMBER

HSIO TECHNOLOGIES, LLC.
13300 67th AVENUE NORTH
MAPLE GROVE, MINNESOTA 55311
763-447-6260

TITLE:
SC KT, 96GRY7.5X13.1-0.80,
W/ EUTECTIC SOLDER BALLS

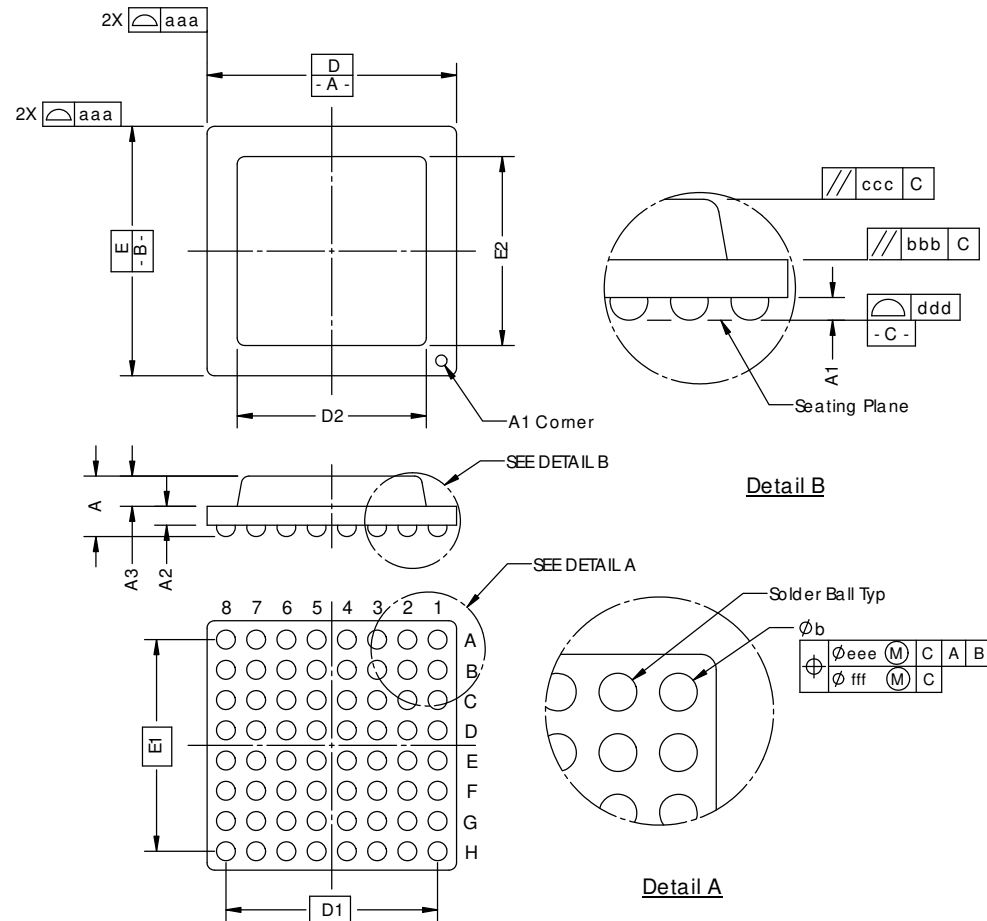
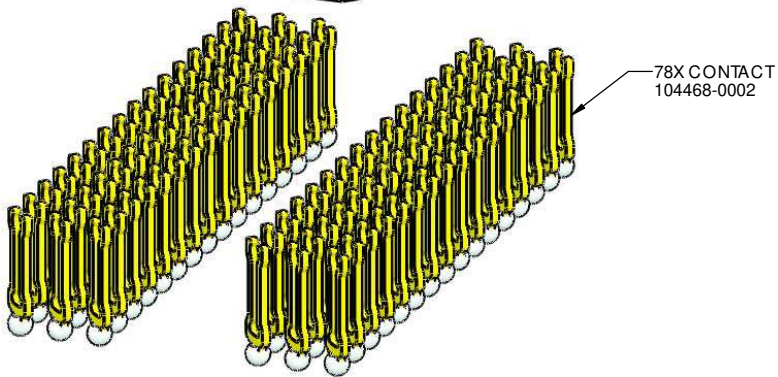
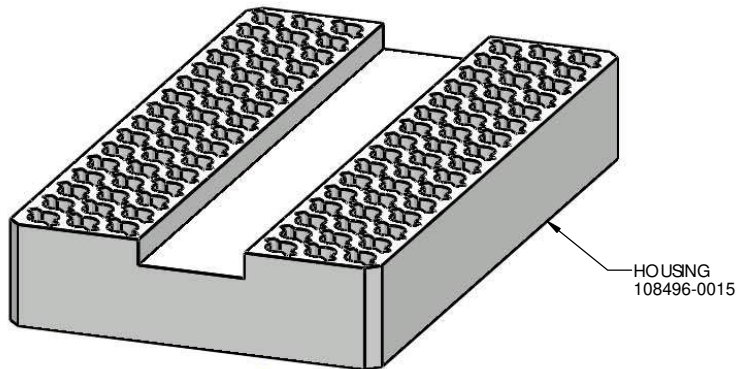
DWG. NO. **108493-0015** REV **A**

SCALE: 10:1 SIZE: C SHEET 1 OF 2


HSIO technologies
PROPRIETARY AND CONFIDENTIAL
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SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	N	96	Package Size	D	7.50
Columns	ND	9		E	13.10
Rows	NE	16	Ball Spacing	D1	6.400
Pitch	e	0.80		E1	12.000
Ball Size	b	0.45±0.05	Encapsulant/ Top Size	D2	n/a
Total Thickness	A	N/A		E2	n/a
Ball Height	A1	0.300 Min	Pattern Style	Irregular*	
Substrate Thickness	A2	N/A	Perimeter Rows	n/a	
Top Thickness	A3		Center Array	n/a	
Form Tolerances					
Edge	aaa	0.20	Bottom	ddd	0.15
Substrate	bbb	0.20	Position	eee	0.20
top	ccc	0.20	Position	fff	0.08

All dimensions are in millimeters.
*See footprint specification for pattern details.



Generic Representation with Full Grid Array

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UNLESS OTHERWISE SPECIFIED:	NAME	DATE	HSIQ TECHNOLOGIES, LLC. 13300 67th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260
DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGULAR ± 1° XX ±0.25 XXX ±0.10 XXXX ±0.050	DRAWN	AS 01/30/14	
LEGEND: △ NOTE CALLOUT ○ REVISION CHANGE ○ ITEM NUMBER	CHECKED	MP 01/30/14	
 HSIQ technologies		TITLE: SC KT, 96GRY7.5X13.1-0.80, W/ EUTECTIC SOLDER BALLS DWG. NO. 108493-0015 REV A SCALE: 10:1 SIZE C SHEET 2 OF 2	